Registration:
The registration is free of charge.
Please send an e-mail for registration with the information whether you would like to attend both days or only one (June 12th or 13th) to events@enas.fraunhofer.de until June 1, 2018.

Hotel:
Until May 24, rooms in Hotel Chemnitzer Hof can be ordered by using the keyword: Seminar System Packaging.
single room (incl. breakfast): 68 EUR
Hotel Chemnitzer Hof, Theaterplatz 4, 09111 Chemnitz
phone: +49 371 684-0 | info@chemnitzer-hof.de

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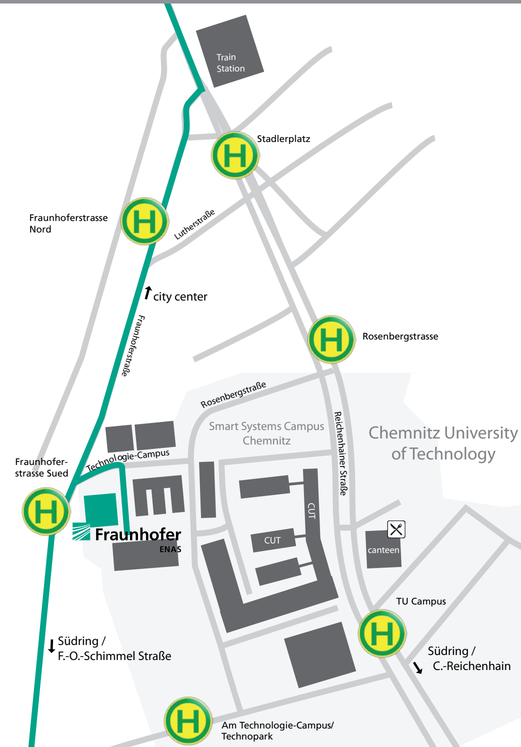
HOW TO REACH US



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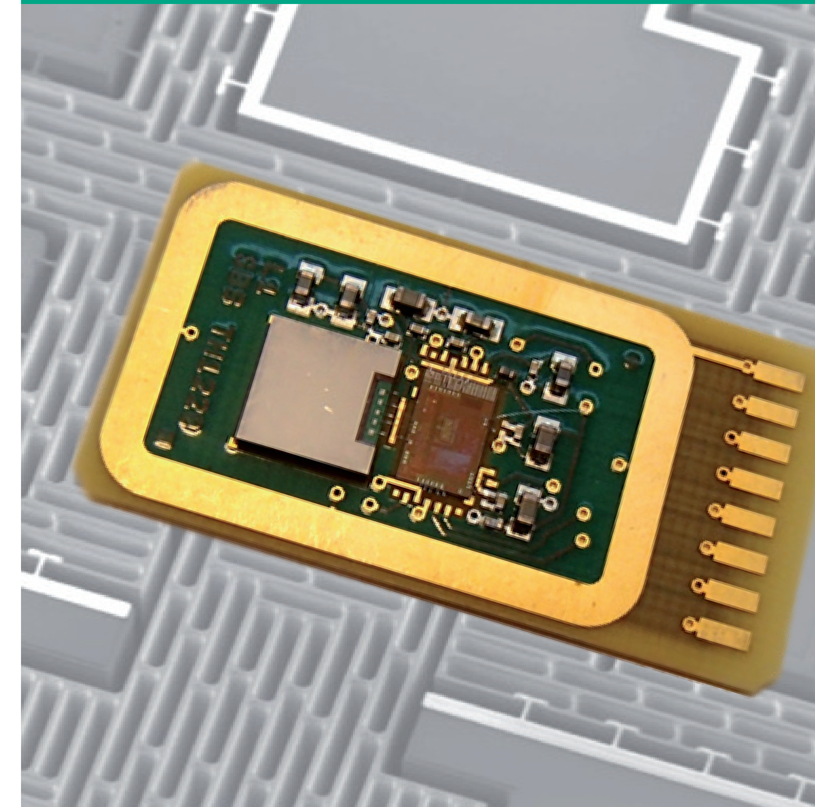
FRAUNHOFER INSTITUTE FOR
ELECTRONIC NANO SYSTEMS ENAS

JUNE 12 AND 13, 2018 | FRAUNHOFER ENAS
TECHNOLOGIE-CAMPUS 3 | 09126 CHEMNITZ

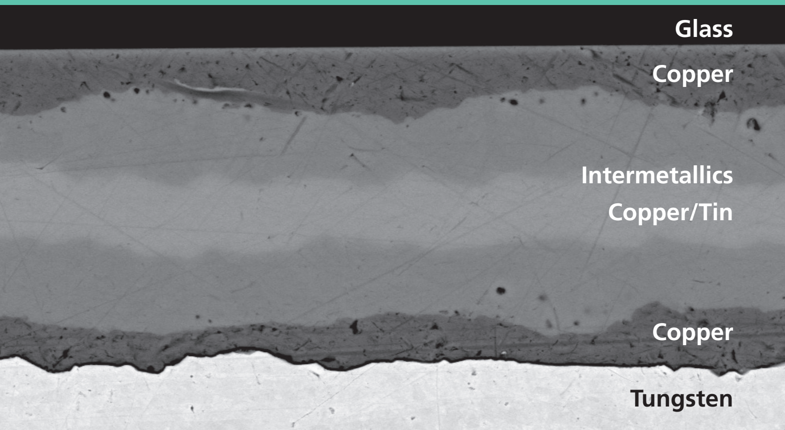
CHEMNITZER SEMINAR

MATERIALS AND TECHNOLOGIES FOR MEMS PACKAGING



PROGRAM

CHEMNITZER SEMINAR
NANOTECHNOLOGY | NANOMATERIALS |
NANORELIABILITY



CHEMNITZER SEMINAR »MATERIALS AND TECHNOLOGIES FOR MEMS PACKAGING«

Smart systems are becoming more and more important in our daily life, e.g. in cars, security applications, medical engineering, condition monitoring, logistics and other applications.
A major bottleneck, however, is the packaging of the sensitive microstructures on different levels to allow them to withstand even harsh environments and meet the competitive market requirements.
In 2018 advanced electronic packaging materials, novel processes and technologies will be highlighted within the 28th Chemnitzer Seminar.
On June 14, our cooperation partner Electronic Design Chemnitz GmbH will held a workshop about »Smart Sensor Technologies«. Find more information online: www.ed-chemnitz.de.

TUESDAY JUNE 12, 2018

12:30 – 12:40 pm	**Welcome |** Dr. Maik Wiemer, Fraunhofer ENAS
12:40 – 1:10 pm	**Keynote: Materials for LED packaging |** Dr. Norwin von Malm, OSRAM Opto Semiconductors GmbH
1:10 – 1:40 pm	**New soldering pastes for diffusion based joining technologies** | Steffen Käss, Heraeus Deutschland GmbH & Co. KG
1:40 – 2:10 pm	**Materials for wafer level packaging, MEMS & semiconductor assembly** | Ruud de Wit, Henkel Electronic Materials NV
2:10 – 2:40 pm	Poster presentation, coffee break and networking
2:40 – 3:10 pm	**Keynote: Glass frit wafer bonding for encapsulating monolithic integrated CMOS-MEMS devices** | Roy Knechtel, X-FAB MEMS Foundry GmbH
3:10 – 3:40 pm	**Glasfritbonding for pressure sensor** | Dr. Timo Kober, Endress+Hauser SE+Co. KG
3:40 – 4:10 pm	**Physical vapor deposition methods for Al/Pd based reactive multilayer systems** | Ina Schmidt, Siegert Thinfilm Technology GmbH
4:10 – 4:40 pm	**Smoothing of metallic thin films using advanced electropolishing technologies** | Jean-François Vanhumbeeck, CRM Group
4:40 – 5:10 pm	**Electroforming and hot embossing of micro- and nanostructured inserts for the manufacturing of biomimetic surfaces** | Dr. Markus Guttmann, KIT – Karlsruhe Institute of Technology
5:10 – 5:40 pm	**Research Fab Microelectronics Germany FMD** | Dr. Stephan Guttowski, Forschungsfabrik Mikroelektronik Deutschland

WEDNESDAY JUNE 13, 2018

9:00 – 9:10 am	**Welcome |** Dr. Maik Wiemer, Fraunhofer ENAS
9:10 – 9:40 am	**Keynote: Panasonic AIS R&D's vision and strategy |** Hidekazu Umeda, European Technology Center in Panasonic Industrial Devices
9:40 – 10:10 am	**Ag-Sintering of bare dies for power devices as an alternative to AuSn soldering** | Ralph Schachler, Finetech GmbH & Co. KG
10:10 – 10:40 am	Poster presentation, coffee break and networking
10:40 – 11:10 am	**Wafer bonding with novel method for improved post-bond alignment for high volume production in MEMS applications** | Thomas Schmidt, SUSS MicroTec Lithography GmbH
11:10 – 11:40 am	**Advances in High Vacuum encapsulation for MEMS packaging based on metallic bonding interfaces** | Dr. Bernhard Rebhan, EV Group
11:40 – 12:10 pm	**Soldering of aluminum with rosin based and inorganic fluxes** | Dr. Nils Kopp, Elsold GmbH
12:10 – 1:10 pm	Lunch
1:10 – 1:40 pm	**Nanotechnology meets temperature-sensitive devices** | Dr. Jan Freitag, CiS Forschungsinstitut für Mikrosensorik GmbH
1:40 – 2:10 pm	Discussion
from 2:10 pm	Individual Lab and Window Tours